GOVERNMENT OF INDIA
MINISTRY OF ELECTRONICS AND INFORMATION TECHNOLOGY
LOK SABHA
UNSTARRED QUESTION NO. 756
TO BE ANSWERED ON: 04.02.2026

INVESTMENT TRENDS IN IT AND SEMICONDUCTORS SECTORS

756. MS KANGNA RANAUT:

Will the Minister of ELECTRONICS AND INFORMATION TECHNOLOGY be pleased to state:

(a) the details of semiconductor-related projects approved by the Government in recent years including the number of projects approved and their broad nature;
(b) the present status of implementation of these approved semiconductor projects including stage of execution and expected timelines for commencement of operations; and
(c) the steps being taken by the Government to strengthen inter-ministerial coordination and transparency in reporting investment trends and project progress in strategic sectors such as Information Technology (IT) and semiconductors?

ANSWER

MINISTER OF STATE FOR ELECTRONICS AND INFORMATION TECHNOLOGY
(SHRI JITIN PRASADA)

(a) to (c): The semiconductor development strategy is inspired by Hon'ble Prime Minister's vision of Atmanirbhar Bharat and Make in India, Make for the world. As part of this strategy, India aims to develop a complete ecosystem, ranging from design, fabrication, assembly, testing, packaging and module manufacturing.

Given the foundational nature of semiconductor industry for the economy, the Government launched the 'Semicon India Programme' with a total outlay of Rs. 76,000 crore for the development of semiconductor and display manufacturing ecosystem in the country. Following are salient achievements under this Programme:

- Government has approved 10 projects with envisaged investments of about Rs. 1.6 Lakh Crore which includes 2 fabs and 8 packaging units. These units inter-alia include CMOS (Silicon) fab, Silicon Carbide fab, advanced packaging, memory packaging, etc. These projects are in various stages of implementation and pilot production has started in 4 units.
- 24 chip design projects have been supported through startups. 16 have completed tapeouts and 13 have received VC funding.
- 350 universities have been provided access to EDA tools, used by 65 thousand engineers

The details of the approved Semiconductor manufacturing facilities are placed in **Annexure**.

Government has setup India Semiconductor Mission (ISM) as nodal agency for appraisal and recommendations of such semiconductor projects. In-addition to the semiconductor experts, the representatives from various ministries/Departments are also present to advise ISM.

For IT Sector, The Government of India is actively promoting its growth, especially in smaller towns and cities. The performance of this sector over the last 5 years and estimates for 2024-25, as published by the National Association of Software and Services Companies (NASSCOM), is mentioned below:

(in USD Billion)

	2020-21	2021-22	2022-23	2023-24	2024-25 (E)
Exports	152	178	194	214.4	224.4
Domestic	45	49	51	54.4	58.2
Total Revenue	196	227	245	269	283

(E) = Estimate

Foreign Direct Investment in ***"Computer Software and Hardware"*** sector and ***"Services"*** in the IT Sector is published online by Department from Promotion of Industries and Internal Trade (DPIIT) on their website on quarterly and yearly basis. Similarly, investment details of approved projects under India Semiconductor Mission are also reported publicly by Press Information Bureau.

****

Annexure

Details of approved semiconductor manufacturing projects:

1. **Micron Technology Inc.** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs.22,516 crore. Micron's facility in India will enable assembly and test manufacturing for both DRAM and NAND products and address demand from domestic and international markets. The production capacity is around 14 million units per week.
2. **Tata Electronics Private Limited (TEPL)** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 91,526 crore. The fab facility will be set up in technology partnership with PSMC, Taiwan. The production capacity of the project would be around 50,000 wafer starts per month (WSPM).
3. **Tata Electronics Private Limited (TEPL)** is establishing semiconductor manufacturing facility in Assam with an investment of Rs.27,120 crores. The facility will use indigenous semiconductor packaging technologies with a production capacity of 48 million units per day.
4. **CG Power and Industrial Solutions Limited** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 7,584 crore. The facility will be set up as a joint venture partnership with Renesas Electronics America Inc., USA, and STARS Microelectronic, Thailand. The Technology would be provided for this facility by Renesas Electronics Corporation, Japan and STARS Microelectronic, Thailand. The production capacity would be around 15.07 million units per day.
5. **Kaynes Technology India Limited (KTIL)** is establishing semiconductor manufacturing facility in Gujarat with an investment of Rs. 3,307 crores for Wire bond Interconnect, Substrate Based Packages. The Technology would be provided by ISO Technology Sdn. Bhd. and AOI Electronics Co. Ltd. (AOI). The facility will have the capacity to produce more than 6.33 million chips per day.
6. **Vama Sundari Investments (Delhi) Private Limited (VSIPL)** is establishing semiconductor manufacturing facility in Uttar Pradesh with an investment of Rs 3,706 crores for display driver ICs (DDIC) using Gold (Au) Bump technology along with chip probing facilities and die processing services. The Technology would be provided by Hon Hai, Taiwan. The facility will be set up as a joint venture partnership between VSIPL and Foxconn, India. The production capacity would be around 20K wafers per month/36 million chips per month.
7. **3D Glass Solutions Inc. (3DGS)** is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 1,943 crores. The plant will handle the assembly of packaged products such as Flip Chip Ball Grid Array (FCBGA) assembly, Radio Frequency System in Package (RF SiP), Antenna in Package System in Package (AiP SiP), glass interposers with passives and silicon bridges and 3D Heterogeneous Integration (3DHI) modules. The Proposed installed capacity for glass panel substrate production, assembly and 3DHI is around 5800 panels per month, 4.20 million units per month, and 1100 units per months respectively.
8. **SiCSem Private Limited** is establishing semiconductor manufacturing facility in Odisha with an investment of Rs. 2,066 crores. The facility will be set up in technology partnership with Clas-SiC Wafer Fab Ltd. for SiC fab and Continental Device India Pvt. Ltd. for packaging. The production capacity is 5,000 wafers/month, and the packaging capacity is 8 million units/month.
9. **Continental Device India Private Limited (CDIL)** is expanding its semiconductor manufacturing facility in Punjab, with an investment of Rs. 117 crores. The facility will manufacture high-power discrete semiconductor devices such as MOSFETs, IGBTs, Schottky Bypass Diodes, and transistors, both in Silicon and Silicon Carbide. The production capacity will be around 158.38 million units/annum.

10. **Advanced System in Package Technologies Private Limited (ASIP)** is establishing semiconductor manufacturing facility in Andhra Pradesh**,** with an investment of Rs. 480 crores. The facility will be set up in technology partnership with APACT Co. Ltd, South Korea. The production capacity of the facility would be around 96 million units/annum.

******